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### ACPL-K49U



Wide Operating Temperature R<sup>2</sup>Coupler<sup>TM</sup> 20 kBd Digital Optocoupler Configurable as Low Power, Low Leakage Phototransistor

# **Data Sheet**



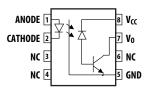
### **Description**

The ACPL-K49U is a single channel, high temperature, high CMR, 20 kBd digital optocoupler, configurable as a low power, low leakage phototransistor, specifically for use in industrial applications. The stretched SO-8 stretched package outline is designed to be compatible with standard surface mount processes.

This digital optocoupler uses an insulating layer between the light emitting diode and an integrated photo detector to provide electrical insulation between input and output. Separate connections for the photodiode bias and output transistor collector increase the speed up to a hundred times over that of a conventional photo-transistor coupler by reducing the base-collector capacitance.

Avago R<sup>2</sup>Coupler isolation product provides with reinforced insulation and reliability that delivers safe signal isolation critical in high temperature industrial applications

### **Functional Diagram**



Note: The connection of a 0.1  $\mu$ F bypass capacitor between pins 5 and 8 is recommended for 5-pin configuration

# ANODE 1 CATHODE 2 NC 3 NC 4 S GND

Note: Pins 7 and 8 are externally shorted for 4-pin configuration

### **Features**

- High Temperature and Reliability low speed digital interface for Industrial Application.
- 30 kV/μs High Common-Mode Rejection at V<sub>CM</sub> = 1500 V (typ)
- Low Power, Low Leakage Phototransistor in a "4-pin Configuration"
- Compact, Auto-Insertable Stretched SO8 Packages
- Wide Temperature Range: -40° C to +125° C
- Low LED Drive Current: 4 mA (typ)
- Low Propagation Delay: 20 μs (max)
- Worldwide Safety Approval:
  - UL 1577 approval, 5 kV<sub>RMS</sub>/1 min.
  - CSA Approval
  - IEC/EN/DIN EN 60747-5-5

### **Applications**

- Industrial Low Speed Digital Signal Isolation Interface
- Inverter Fault Feedback Signal Isolation
- Switching Power Supplies Feedback Circuit

### **Truth Table**

LED	Vo
ON	LOW
OFF	HIGH

### **Ordering Information**

Specify part number followed by option number (if desired).

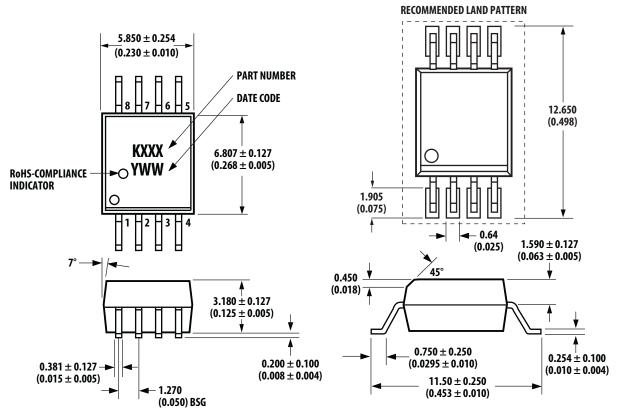
	Option		Surface	Tape	UL 5000 V <sub>rms</sub> /	
Part number	(RoHS Compliant)	Package	Mount	& Reel	1 Minute rating	Quantity
ACPL-K49U	-000E	Stretched	Χ		Χ	80 per tube
	-500E	SO-8	X	Х	X	1000 per reel

To order, choose a part number from the part number column and combine with the desired option from the option column to form an order entry.

### Example 1:

ACPL-K49U-500E to order product of SSO-8 Surface Mount package in Tape and Reel packaging with RoHS compliance. Option datasheets are available. Contact your Avago sales representative or authorized distributor for information.

### **Outline Drawing (Stretched S08)**



Dimensions in millimeters and (inches).

Note:

Lead coplanarity = 0.1 mm (0.004 inches). Floating lead protrusion = 0.25mm (10mils) max.

### **Recommended Pb-Free IR Reflow Profile**

Recommended reflow condition as per JEDEC Standard, J-STD-020 (latest revision).

Note: Non-halide flux should be used

## **Regulatory Information**

The ACPL-K49U is approved by the following organizations:

### UL

Approval under UL 1577, component recognition program up to  $V_{ISO} = 5 \text{ kV}_{RMS}$ .

### CSA

Approval under CSA Component Acceptance Notice #5.

### **IEC/EN/DIN EN 60747-5-5**

Approval under IEC/EN/DIN EN 60747-5-5

### **Insulation and Safety Related Specifications**

Parameter	Symbol	ACPL-K49U	Units	Conditions
Minimum External Air Gap (Clearance)	L(101)	8	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (Creepage)	L(102)	8	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	mm	Through insulation distance conductor to conductor, usually the straight line distance thickness between the emitter and detector.
Tracking Resistance (Comparative Tracking Index)	CTI	175	V	DIN IEC 112/VDE 0303 Part 1
Isolation Group (DIN VDE0109)		Illa		Material Group (DIN VDE 0109)

### IEC/EN/DIN EN 60747-5-5 Insulation Related Characteristic

Description	Symbol	Characteristic	Units
Installation classification per DIN VDE 0110/1.89, Table 1			
for rated mains voltage ≤ 150 V <sub>rms</sub>		I-IV	
for rated mains voltage $\leq$ 300 $V_{rms}$		I-IV	
for rated mains voltage $\leq 450  V_{rms}$		I-IV	
for rated mains voltage $\leq$ 600 $V_{rms}$		I-IV	
for rated mains voltage ≤ 1000 V <sub>rms</sub>		1-111	
Climatic Classification		40/125/21	
Pollution Degree (DIN VDE 0110/1.89)		2	
Maximum Working Insulation Voltage	$V_{IORM}$	1140	V <sub>PEAK</sub>
Input to Output Test Voltage, Method b	$V_{PR}$	2137	$V_{PEAK}$
$V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Test with $t_m = 1$ sec			
Partial Discharge < 5 pC			
Input to Output Test Voltage, Method a	$V_{PR}$	1824	$V_{PEAK}$
$V_{IORM} \times 1.6 = V_{PR}$ , Type and sample test, $t_m = 10$ sec,			
Partial Discharge < 5 pC			
Highest Allowable Overvoltage (Transient Overvoltage, t <sub>ini</sub> = 60 sec)	$V_{IOTM}$	8000	V <sub>PEAK</sub>
Safety Limiting Values (Maximum values allowed in the event of a failure)			
Case Temperature	$T_S$	175	°C
Input Current	I <sub>S,INPUT</sub>	230	mA
Output Power	Ps,OUTPUT	600	mW
Insulation Resistance at $T_S$ , $V_{IO} = 500 \text{ V}$	$R_S$	10 <sup>9</sup>	Ω

# **Absolute Maximum Ratings**

Parameter	Symbol	Min.	Max.	Units	Note	
Storage Temperature		Ts	-55	150	°C	
Operating Temperature		T <sub>A</sub>	-40	125	°C	
Lead Soldering Cycle	Temperature			260	°C	
	Time			10	S	
Average Forward Input Curre	nt	I <sub>F(avg)</sub>		20	mA	
Peak Forward Input Current (5	50% duty cycle, 1ms pulse width)	I <sub>F(peak)</sub>		40	mA	
Peak Transient Input Current (	(< = 1 μs pulse width, 300 ps)	I <sub>F(trans)</sub>		100	mA	
Reversed Input Voltage		V <sub>R</sub>		5	V	
Input Power Dissipation		P <sub>IN</sub>		30	mW	
Output Power Dissipation		Po		100	mW	
Average Output Current		Io		8	mA	
Peak Output Current		I <sub>o(pk)</sub>		16	mA	
Supply Voltage		V <sub>CC</sub>	-0.5	30	V	
Output Voltage		Vo	-0.5	20	V	

# **Recommended Operating Conditions**

Parameter	Symbol	Min.	Max.	Units	Note
Supply Voltage	$V_{CC}$		20.0	V	
Operating Temperature	T <sub>A</sub>	-40	125	°C	

# Electrical Specifications (DC) for 5-Pin Configuration

Over recommended operating  $T_A = -40^{\circ} \, \text{C}$  to  $125^{\circ} \, \text{C}$ , unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions			Fig.	Note
Current Transfer Ratio	CTR	32	65	100	%	T <sub>A</sub> = 25° C	$Vcc = 4.5 \text{ V}, V_o = 0$	0.5 V, I <sub>F</sub> = 10 mA	1,2,4	1
		24	65				_			
		65	110	150		$T_A = 25^{\circ} C$	$Vcc = 4.5 \text{ V}, V_0 = 0.5 \text{ V}, I_F = 4 \text{ mA}$		1,2,4	_
		50	110				_			_
Logic Low Output Voltage	V <sub>OL</sub>		0.1	0.5	V		I <sub>F</sub> = 10 mA	Vcc = 4.5 V,	3	
			0.1	0.4			$I_F = 4 \text{ mA}$	$I_0 = 2.4 \text{ mA},$		
Logic High Output Current	I <sub>OH</sub>		2x10 <sup>-4</sup>	0.5	μΑ	T <sub>A</sub> = 25° C	$V_0 = V_{cc} = 5.5 \text{ V}$	$I_F = 0 \text{ mA}$	7	
			4x10 <sup>-4</sup>	5	<del></del>		$V_0 = V_{cc} = 20 \text{ V}$			_
Logic Low Supply Current	I <sub>CCL</sub>		35	100	μΑ		$I_F = 4 \text{ mA}, V_0 = \text{op}$	pen, $V_{cc} = 20 \text{ V}$		
Logic High Supply	I <sub>CCH</sub>		0.02	1	μΑ	$T_A = 25^{\circ} C$	$I_F = 0 \text{ mA}, V_0 = \text{open}, V_{cc} = 20 \text{ V}$			
Current				2.5	μΑ		_			
Input Forward Voltage	V <sub>F</sub>	1.4	1.5	1.7	V	T <sub>A</sub> = 25° C	$I_F = 4 \text{ mA}$		6	
		1.2	1.5	1.8	V					
Input Reversed Breakdown Voltage	$BV_R$	5			V		$I_R = 10  \mu A$			
Temperature Coefficient of Forward Voltage	ΔV/ΔΤΑ		-1.5		mV/ºC		I <sub>F</sub> = 10 mA			
Input Capacitance	C <sub>IN</sub>		90		рF		$F = 1 MHz, V_F = 0$	V		

# Switching Specifications (AC) for 5-Pin Configuration

Over recommended operating ( $T_A = -40^{\circ}$  C to 125° C),  $V_{CC} = 5.0$  V unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions		Fig.	Note
Propagation Delay Time to Logic Low at Output	t <sub>PHL</sub>			20	μs	$I_F = 4 \text{ mA}, V$	Pulse: f = 10 kHz, Duty cycle = 50%, $I_F = 4$ mA, $V_{CC} = 5.0$ V, $R_L = 8.2$ kΩ, $C_L = 15$ pF, $V_{THHL} = 1.5$ V		
Propagation Delay Time to Logic High at Output	t <sub>PLH</sub>			20	μs	$I_F = 4 \text{ mA}, V$	Pulse: $f = 10$ kHz, Duty cycle = 50%, $I_F = 4$ mA, $V_{CC} = 5.0$ V, $R_L = 8.2$ kΩ, $C_L = 15$ pF, $V_{THLH} = 2.0$ V		
Common Mode Transient Immunity at Logic High Output	CM <sub>H</sub>	15	30		kV/μs	$I_F = 0 \text{ mA}$	$V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ} C$ $R_L = 1.9 \text{ k}\Omega$	10	4
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	15	30		kV/vs	$I_F = 10 \text{ mA}$	_		
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>		15		kV/μs	I <sub>F</sub> = 4 mA	$V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ} C$ $R_L = 8.2 \text{ k}\Omega$		

# **Electrical Specifications (DC) for 4-Pin Configuration**

Over recommended operating  $T_A = -40^{\circ}$  C to  $125^{\circ}$  C, unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions	Fig.	Note
Current Transfer Ratio	CTR	70	130	210	%	$T_A = 25^{\circ} \text{ C}, V_{CC} = V_O = 5 \text{ V}, I_F = 4 \text{ mA}$	4	1
Current Transfer	CTR	24	60			$I_F = 10 \text{ mA}$ $V_{CC} = V_O = 0.5 \text{ V}$	5	
Ratio	(Sat)	35	110		_	I <sub>F</sub> = 4 mA		
Logic Low Output	V <sub>OL</sub>		0.1	0.5	V	$I_F = 10 \text{ mA}$ $I_O = 2.4 \text{ mA}$	5	
Voltage			0.1	0.5		$I_F = 4 \text{ mA}$ $I_O = 1.4 \text{ mA}$		
Off-State Current	I <sub>(CEO)</sub>		4x10 <sup>-4</sup>	5	μΑ	$V_O = V_{CC} = 20 \text{ V, I}_F = 0 \text{ mA}$	8	
Input Forward	$V_{F}$	1.4	1.5	1.7	V	$T_A = 25^{\circ} \text{ C}$ $I_F = 4 \text{ mA}$	6	
Voltage		1.2	1.5	1.8	V			
Input Reversed Breakdown Voltage	$BV_R$	5			V	$I_R = 10 \mu A$		
Temperature Coefficient of Forward Voltage	$\Delta V/\Delta T_A$		-1.5		mV/°C	I <sub>F</sub> = 10 mA		
Input Capacitance	C <sub>IN</sub>		90		рF	$F = 1 \text{ MHz}, V_F = 0 \text{ V}$		
output Capacitance	C <sub>CE</sub>		35		рF	$F = 1 \text{ MHz}, V_F = 0 \text{ V}, V_O = V_{CC} = 0 \text{ V}$		

### Switching Specifications (AC) for 4-Pin Configuration

Over recommended operating (T<sub>A</sub> = -40° C to 125° C),  $V_{CC}$  = 5.0 V unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions	Fig.	Note	
Propagation Delay Time to Logic Low at Output	t <sub>PHL</sub>		2	100	μs	$V_{CC} = 5.0 \text{ V}$	Pulse: $f=1$ kHz, Duty cycle = 50%, $I_F=4$ mA, $V_{CC}=5.0$ V, $R_L=8.2$ k $\Omega$ , $C_L=15$ pF, $V_{THHL}=1.5$ V		
Propagation Delay Time to Logic High at Output	t <sub>PLH</sub>		19	100	μs	$V_{CC} = 5.0 \text{ V}$	Pulse: f = 1 kHz, Duty cycle = 50%, $I_F$ = 4 mA, $V_{CC}$ = 5.0 V, $R_L$ = 8.2 k $\Omega$ $C_L$ = 15 pF, $V_{THLH}$ = 2.0 V		
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	15	30		kV/μs	$I_F = 0 \text{ mA}$	$\begin{aligned} V_{CM} &= 1500  V_{p\text{-}p}, T_A = 25^\circ  C \\ R_L &= 8.2  k\Omega \end{aligned}$	12	4
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	15	30		kV/μs	$I_F = 4 \text{ mA}$	$V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ} C$ $R_L = 8.2 \text{ k}\Omega$		

### **Package Characteristics**

Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions	Fig.	Note
Input-Output Momentary Withstand Voltage*	$V_{ISO}$	5000			$V_{RMS}$	RH $\leq$ 50%, t = 1 min; T <sub>A</sub> = 25° C		2, 3
Input-Output Resistance	$R_{I-O}$		10 <sup>14</sup>		Ω	$V_{I-O} = 500  Vdc$		2
Input-Output Capacitance	C <sub>I-O</sub>		0.6		рF	$f = 1 \text{ MHz}; V_{I-O} = 0 V_{DC}$		2

<sup>\*</sup> The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating.

### Notes:

- 1. Current Transfer Ratio in percent is defined as the ratio of output collector current, I<sub>O</sub>, to the forward LED input current, I<sub>F</sub>, times 100.
- 2. Device considered a two terminal device: pins 1, 2, 3 and 4 shorted together, and pins 5, 6, 7 and 8 shorted together.
- 3. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage  $\geq$  6000 V<sub>RMS</sub> for 1 second.
- 4. Common transient immunity in a Logic High level is the maximum tolerable (positive)  $dV_{CM}/dt$  on the rising edge of the common mode pulse,  $V_{CM}$ , to assure that the output will remain in a Logic High state (i.e.,  $V_{CM}$ ). Common mode transient immunity in a Logic Low level is the maximum tolerable (negative)  $dV_{CM}/dt$  on the falling edge of the common mode pulse signal,  $V_{CM}$  to assure that the output will remain in a Logic Low state (i.e.,  $V_{CM}$ ).

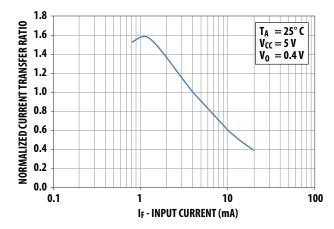


Figure 1. Current Transfer Ratio vs. Input Current

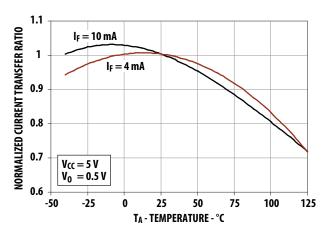


Figure 2. Normalized Current Transfer Ratio vs. Temperature

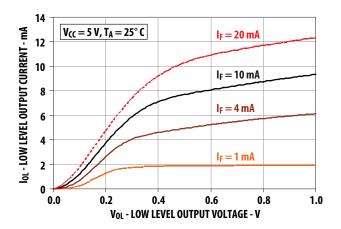


Figure 3. Typical Low Level Output Current vs Output Voltage

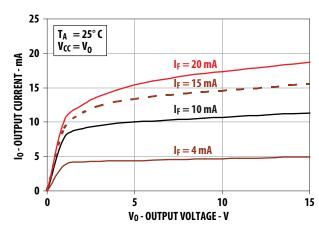


Figure 4. Output Current vs Output Voltage (4-Pin Configuration)

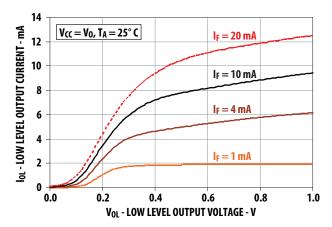


Figure 5. Typical Low Level Output Current vs Output Voltage (4-Pin Configuration)

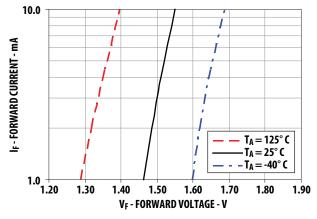
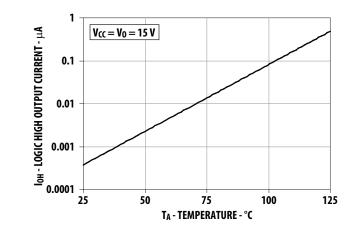


Figure 6. Typical Input Current vs Forward Voltage



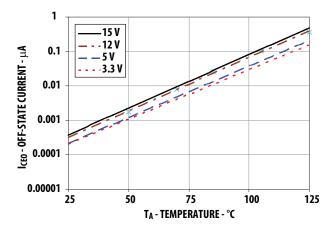


Figure 7. Typical High Level Output Current vs Temperature

Figure 8. Typical Off-State Current vs Temperature (4-Pin Configuration)

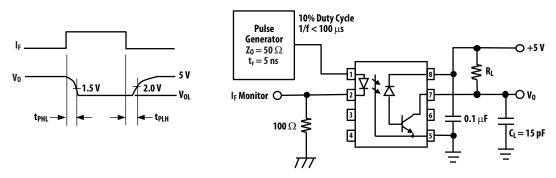


Figure 9. Switching Test Circuit (5-Pin Configuration)

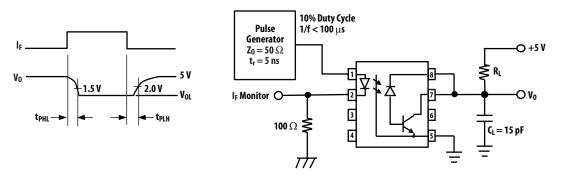


Figure 10. Switching Test Circuit (4-Pin Configuration)

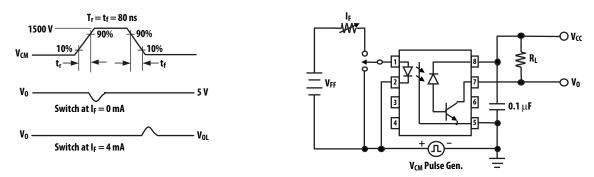
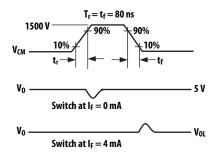


Figure 11. Test Circuit for Transient Immunity and Typical Waveforms (5-Pin Configuration)



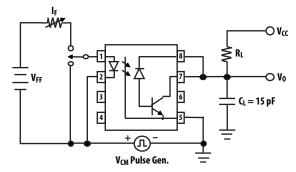


Figure 12. Test Circuit for Transient Immunity and Typical Waveforms (4-Pin Configuration)

### Thermal Resistance Model for ACPL-K49U

The diagram of ACPL-K49U for measurement is shown in Figure 13. Here, one die is heated first and the temperatures of all the dice are recorded after thermal equilibrium is reached. Then, the 2<sup>nd</sup> die is heated and all the dice temperatures are recorded. With the known ambient temperature, the die junction temperature and power dissipation, the thermal resistance can be calculated. The thermal resistance calculation can be cast in matrix form. This yields a 2 by 2 matrix for our case of two heat sources.

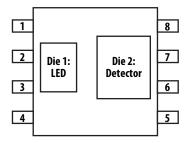


Figure 13, Diagram of ACPL-K49U for measurement

$$\left|\begin{array}{cc|c} R_{11} & R_{12} \\ R_{21} & R_{22} \end{array}\right| \left|\begin{array}{cc|c} X & P_1 \\ P_2 \end{array}\right| = \left|\begin{array}{cc|c} \Delta T_1 \\ \Delta T_2 \end{array}\right|$$

R<sub>11</sub>: Thermal Resistance of Die1 due to heating of Die1

R<sub>12</sub>: Thermal Resistance of Die1 due to heating of Die2.

R<sub>21</sub>: Thermal Resistance of Die2 due to heating of Die1.

R<sub>22</sub>: Thermal Resistance of Die2 due to heating of Die2.

P<sub>1</sub>: Power dissipation of Die1 (W).

P<sub>2</sub>: Power dissipation of Die2 (W).

T<sub>1</sub>: Junction temperature of Die1 due to heat from all dice (°C).

T<sub>2</sub>: Junction temperature of Die2 due to heat from all dice.

Ta: Ambient temperature.

 $\Delta T_1$ : Temperature difference between Die1 junction and ambient (°C).

 $\Delta T_2$ : Temperature deference between Die2 junction and ambient (°C).

$$T_1 = (R_{11} \times P_1 + R_{12} \times P_2) + T_a$$

$$T_2 = (R_{21} \times P_1 + R_{22} \times P_2) + T_a$$

Measurement data on a low K board:

$$R_{11} = 160$$
°C/W,  $R_{12} = R_{21} = 74$ °C/W,  $R_{22} = 115$ °C/W

For product information and a complete list of distributors, please go to our web site: **www.avagotech.com** 

